Docket No.: TESSERA 3.3-008 CIP DIV CONT

REMARKS

The present Amendment is in response to the Office Action mailed October 17, 2003 in the above-identified patent application. Enclosed herewith is a Petition requesting a two-month extension of time for resetting the deadline for responding to the Office Action from January 17, 2004, to and including March 17, 2004.

As an initial matter, Applicants acknowledge and appreciate the Examiner's willingness to conduct a telephone interview for the above-identified application on March 4, 2004. Applicants' attorneys appreciate the Examiner's helpful comments provided during the telephone interview.

Examiner rejected claims 1-6 and 8-27 under second paragraph, as being indefinite. U.S.C. § 112, Specifically, the Examiner rejected the above listed claims asserting that the term "frangible" is a vague relative term of In response, Applicants direct the Examiner's attention to the comments provided on page 7 of a Preliminary Amendment In addition, Applicants have amended filed June 17, 2003. independent claims 1 and 27 to recite leads having a "frangible section disposed between the first and second ends of said said frangible section having a crossconnection section, sectional area that is smaller than a cross-sectional area of said connection section." Support for the changes made to independent claims 1 and 27 is found in the specification at, inter alia, page 6, lines 13-17 and FIGS. 2 and 24. In view of the above-noted amendments to claims 1 and 27, all of the pending claims are deemed to satisfy the requirement of U.S.C. § 112, second paragraph, and are otherwise allowable.

The Examiner rejected claims 1, 4-6, 8-9 and 15-26 under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent 4,380,042 to Angelucci. Claim 1 is unanticipated by Angelucci because the reference does not disclose a "support structure adapted for engagement with a semiconductor chip having a top surface, a bottom surface, and a gap extending through said support structure beneath said surfaces and defining first and second portions of said support structure on opposite sides of

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said gap [and] a semiconductor chip disposed between said bottom of said support structure." Claim is surface unanticipated by Angelucci because the reference does not disclose a lead having a "frangible section disposed between the first and second ends of said connection section, said frangible section having a cross-sectional area that is smaller than a cross-sectional area of said connection section." Claims 4-6, 8-9 and 17-26 are unanticipated, inter alia, by virtue of their dependence from claim 1, which is unanticipated for the reasons set forth above.

Claim 15 is unanticipated by Angelucci because the cited reference does not disclose a connection component with "the frangible lead section of each lead having a pair of notches extending horizontally inwardly from said opposed edges to define a neck having a width less than the width between said edges." Claim 15 is also unanticipated, inter alia, by virtue of its dependence from claim 1, which is unanticipated for the reasons set forth above. Claim 16 is unanticipated by virtue of its dependence from claim 15 which is unanticipated for the reasons set forth above.

Claim 27 is unanticipated by Angelucci because the cited reference neither discloses nor suggests a semiconductor chip mounting component including "a support structure adapted for engagement with a semiconductor chip having a top surface, a surface, and a gap extending through said bottom structure between said surfaces and defining first and second portions of said support structure on opposite sides of said gap [and] a semiconductor chip disposed beneath said bottom surface of said support structure." Independent claim 27 unanticipated by Angelucci because the cited reference does not disclose a plurality of electrically conductive leads including a "frangible section disposed between the first and second ends of said connection section, said frangible section having a cross-sectional area that is smaller than a cross-sectional area of said connection section so that said frangible section is mechanically weaker than said first and second ends of said connection section."

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For the above reasons, claims 1, 4-6, 8-9 and 15-27 are deemed unanticipated by Angelucci and are otherwise allowable.

The Examiner rejected claims 1, 4-6, 8-14 and 17-27 § 102(e) as being anticipated U.S. Patent under 35 U.S.C. 4,801,999 to Hayward et al. As noted above, independent claims have been amended. Independent claim unanticipated by Hayward because the cited reference neither discloses nor suggests a semiconductor chip mounting component including a plurality of electrically conductive leads having a "frangible section disposed between the first and second ends of said connection section, said frangible section having a crosssectional area that is smaller than a cross-sectional area of Claims 4-6, 8-14 and 17-26 are said connection section." unanticipated, inter alia, by virtue of their dependence from Independent claim 27 is unanticipated by Hayward because the cited reference neither discloses nor suggests a semiconductor chip mounting component including a plurality of electrically conductive leads having "a frangible disposed between the first and second ends of said connection section, said frangible section having a cross-sectional area that is smaller than a cross-sectional area of said connection section so that said frangible section is mechanically weaker than said first and second ends of said connection section."

For the above reasons, claims 1, 4-6, 8-14 and 17-27 are unanticipated by Hayward and are otherwise allowable.

The Examiner rejected claims 1-6 and 8-27 under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent 5,459,634 to Nelson et al. Independent claim 1 is unanticipated by Nelson because the cited reference neither discloses nor suggests a semiconductor chip mounting component including a plurality of electrically conductive leads, each lead having "a frangible section disposed between the first and second ends of said connection section, said frangible section having a cross-sectional area that is smaller than a cross-sectional area of said connection section." Claims 2-6, 8-14 and 16-26 are unanticipated, inter alia, by virtue of their dependence from

claim 1, which is unanticipated for the reasons set forth above. Claim 15 is unanticipated by Nelson et al. because the cited reference does not disclose a semiconductor chip mounting component with "the frangible lead section of each lead having a pair of notches extending horizontally inwardly from said opposed edges to define a neck having a width less than the width between said edges." Claim 15 is also unanticipated, inter alia, by virtue of its dependence from claim 1, which is unanticipated for the reasons set forth above. Claim 16 is unanticipated by virtue of its dependence from claim 15 which is unanticipated for the reasons set forth above.

Independent claim 27 is unanticipated by Nelson because the cited reference neither discloses nor suggests a semiconductor chip mounting component including a plurality of electrically conductive leads, each lead having a "frangible section disposed between the first and second ends of said connection section, said frangible section having a cross-sectional area that is smaller than a cross-sectional area of said connection section so that said frangible section is mechanically weaker than said first and second ends of said connection section."

The Examiner rejected claims 1, 4, 6, 8, 10-14, 17, and 19-27 under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent 5,550,406 to McCormick and U.S. Patent 5,459,634 to Independent claim 1 is unobvious over McCormick Nelson et al. and Nelson because the cited references neither disclose nor semiconductor chip mounting component having a plurality of electrically conductive leads, each lead having a "frangible section disposed between the first and second ends of said connection section, said frangible section having a crosssectional area that is smaller than a cross-sectional area of said connection section." Claims 4, 6, 8, 10-14, 17, and 19-26 are unobvious, inter alia, by virtue of their dependence from claim 1, which is unobvious for the reasons set forth above.

Independent claim 27 is unobvious over McCormick and Nelson because the cited references neither disclose nor suggest a semiconductor chip mounting component including a plurality of

electrically conductive leads, each lead having a "frangible section disposed between the first and second ends of said connection section, said frangible section having a cross-sectional area that is smaller than a cross-sectional area of said connection section so that said frangible section is mechanically weaker than said first and second ends of said connection section."

As it is believed that all of the rejections set forth in the Official Action have been fully met, favorable reconsideration and allowance are earnestly solicited.

If, however, for any reason the Examiner does not believe that such action can be taken at this time, it is respectfully requested that he telephone Applicants' attorney at (908) 654-5000 in order to overcome any additional objections which he might have.

If there are any additional charges in connection with this requested amendment, the Examiner is authorized to charge Deposit Account No. 12-1095 therefor.

Dated: March 9, 2004

Respectfully submitted,

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